Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-8 (cancelled).

Claim 9 (currently amended). A method for ~~enabling semiconductor devices to be tested~~ testing wafer-level memory chips having memory cells, the method which comprises:

writing to the memory cells so that the memory cells have stored information;

with a tunable light source, projecting light having a specific wavelength and a specific intensity onto the ~~semiconductor devices~~ wafer-level memory chips for a predetermined time so that irradiated electrons in defective ones of the ~~semiconductor devices~~ wafer-level memory chips, in which a distance between a valence band and a conduction band has a lower value as compared with that of defect-free ones of the ~~semiconductor devices~~ wafer-level memory chips, are transferred into the conduction band from the valence band; and

separating out ones of the memory cells that cannot retain the stored information.

Claim 10 (cancelled). The method according to claim 9, which comprises providing the semiconductor chips as wafer-level memory chips.

Claim 11 (previously presented). The method according to claim 9, which comprises constructing the tunable light source to regulate a frequency of the light in a continuously variable manner.

Claim 12 (previously presented). The method according to claim 9, which comprises constructing a wafer sampler providing a housing for the light source.

Claim 13 (currently amended). The method according to claim 9, which comprises:

providing a surface for positioning the ~~semiconductor devices~~ wafer-level memory chips thereon; and

moveably disposing a component selected from the group consisting of the tunable light source and the surface to

adjust a relative position between the tunable light source and the surface.

Claim 14 (currently amended). The method according to claim 9, which comprises providing the tunable light source with optical fibers having ends, the ends of the optical fibers for projecting the light onto the ~~semiconductor devices~~ wafer-level memory chips.

Claim 15 (cancelled). The method according to claim 9, which comprises providing the ~~semiconductor devices~~ wafer-level memory chips as memory chips having memory cells that have been written to.

Claim 16 (currently amended). The method according to claim 9, which comprises providing a voltage supply for supplying a voltage to the ~~semiconductor devices~~ wafer-level memory chips during testing of the ~~semiconductor devices~~ wafer-level memory chips.